

## • General Description

The AGM55P10C combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{\text{DS(ON)}}$ .

This device is ideal for load switch and battery protection applications.

### Features

- Advance high cell density Trench technology
- Low R<sub>DS(ON)</sub> to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

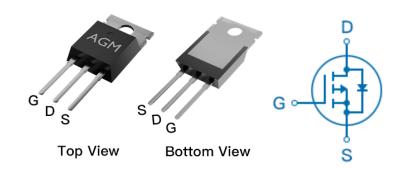
#### Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

## **Product Summary**

BVDSS	RDSON	ID
-100V	52mΩ	-38A

**TO-220 Pin Configuration** 



**Package Marking and Ordering Information** 

Dev	vice Marking	Device	Device Package	Reel Size	Tape width	Quantity
A	GM55P10C	AGM55P10C	TO-220			1000

### Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	-100	V
VGS	Gate-Source Voltage (VDS=0V) ±20		V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	-38	А
טו	Drain Current-Continuous(Tc=100℃)	-23	А
IDM (pluse)	Drain Current-Pulsed (Note 2)	-152	А
	Maximum Power Dissipation(Tc=25℃)	50	W
PD	Maximum Power Dissipation(Tc=100℃)	20	w
EAS	Avalanche energy (Note 3)	240	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$

### Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>		50	°C/W
RøJC	Thermal Resistance Junction-Case <sup>1</sup>		2.5	°C/W



Table 3. Electrical Characteristics (TJ=25℃ unless otherwise noted)

Table 3. Electrical Characteristics (TJ=25 ℃ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off St	ates					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=-250μA	-100			V
IDSS	Zero Gate Voltage Drain Current	VDS=-100V,VGS=0V			-1	μΑ
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=-250µA	-1.2	-1.6	-2.2	٧
gFS	Forward Transconductance	VDS=-5V,ID=-5A		18		S
RDS(on)	Drain-Source On-State Resistance	VGS=-10V, ID=-10A		52	68	mΩ
		VGS=-4.5V, ID=-5A		63	73	mΩ
Dynamic	Characteristics					
Ciss	Input Capacitance			3500		pF
Coss	Output Capacitance	VDS=-40V,VGS=0V F=1MHZ		106		pF
Crss	Reverse Transfer Capacitance	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		90		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		2.2		Ω
Switching	Times					
td(on)	Turn-on Delay Time			49		nS
tr	Turn-on Rise Time	VGS=-10V,VDS=-50V,		71		nS
td(off)	Turn-Off Delay Time	ID=-10A,RGEN=4.5Ω		555		nS
tf	Turn-Off Fall Time			187		nS
Qg	Total Gate Charge			773		nC
Qgs	Gate-Source Charge	VGS=-10V, VDS=-50V, ID=-10A		17		nC
Qgd	Gate-Drain Charge	- VDO30V, ID10A		9.1		nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)				-38	Α
VSD	Forward on Voltage	VGS=0V,IS=-10A			-1.2	٧
trr	Reverse Recovery Time	Isd=-10A ,		32		ns
Qrr	Reverse Recovery Charge	dl/dt=100A/µs , TJ=25℃		49		nc

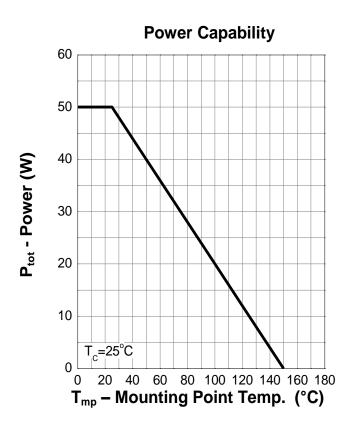
Notes 1. The maximum current rating is package limited.

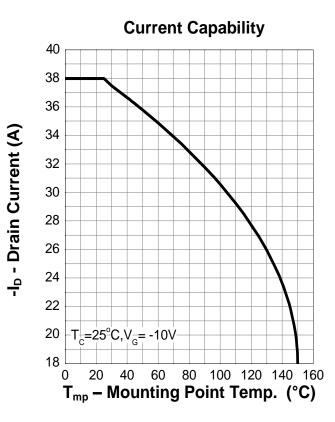
Notes 2. Repetitive Rating: Pulse width limited by maximum junction temperature

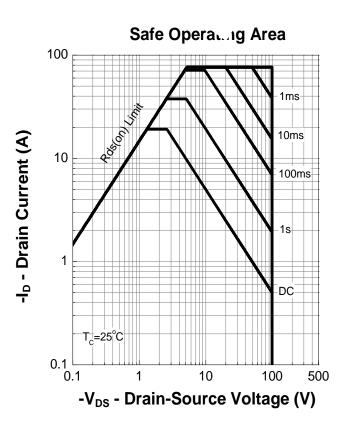
Notes 3.EAS condition: TJ=25  $^{\circ}\text{C}$  , VDD=-50V,Vgs=-10V,ID=-31A, L=0.5mH,RG=25ohm

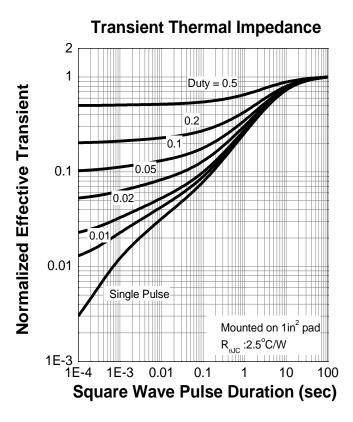


# **Typical Characteristics**



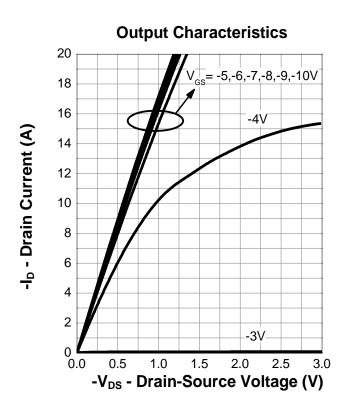


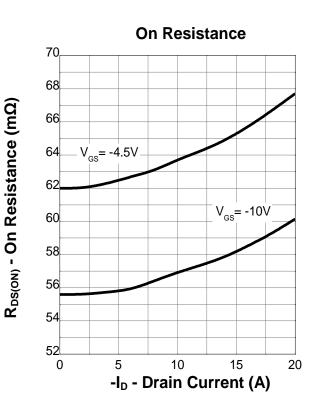


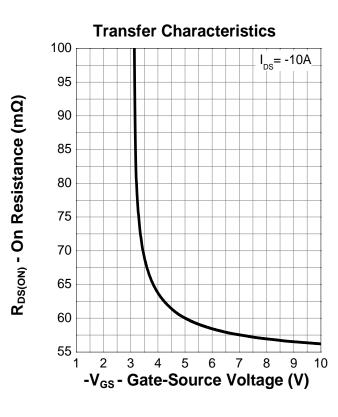


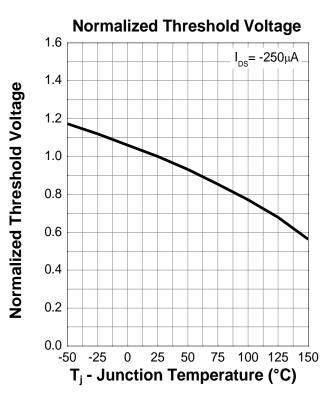


# **Typical Characteristics (cont.)**



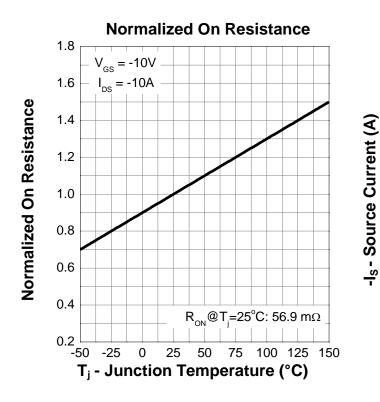


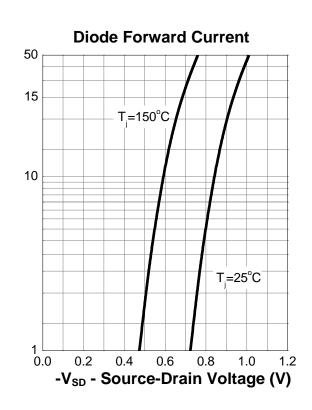


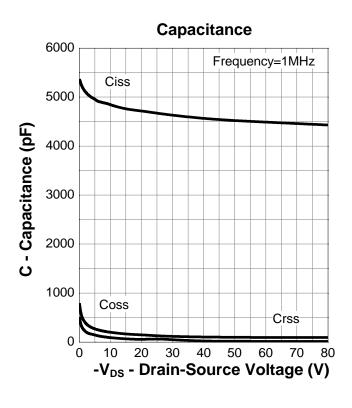


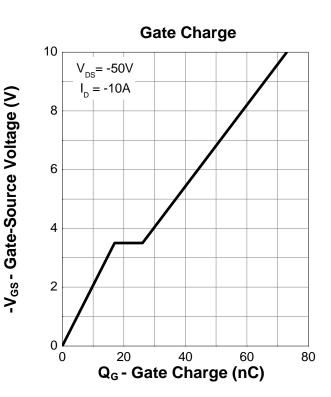


# **Typical Characteristics (cont.)**



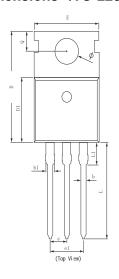


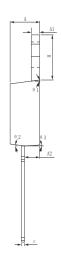


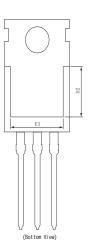




# •Dimensions (TO-220)

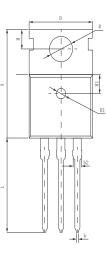


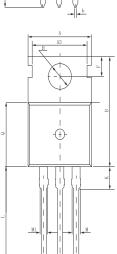




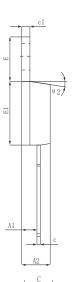
SYMBOL		MILLIMETER	
SIMDUL	MIN	Typ.	MAX
A	4.370	4.570	4. 700
A1	1.250	1.300	1.400
A2	2.150	2. 350	2. 550
b	0.700	0.800	0.950
b1	1.170	1. 270	1.470
С	0.450	0.500	0.600
D	15. 100	15.600	16.100
D1	8.800	9. 100	9.400
D2	5.500	6.300 REF	
Е	9.700	10.000	10.300
E3	7.000	7.600 REF	
е	2. 540 BSC		
e1	5. 080 BSC		
L	13. 200	13.500	13.800
L1		3. 100	3. 400
Н	6.250	6.500	1. 352
Φ	3.400	3. 600	3.800
Q	2.600	2.800	3.000
θ 1	7° TYP		
θ2	7° TYP		
θ3	3° TYP		

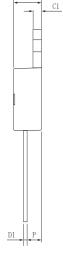


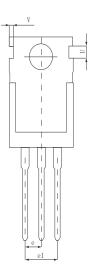


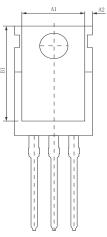












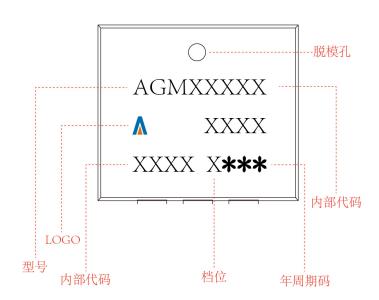
ounmor.	MILLIMETER		
SYMBOL	MIN	Typ.	MAX
A	15.400	15. 600	15.800
A1	2. 350	2. 400	2. 500
A2	4.400	4. 500	4. 700
b	0.700	0.800	0. 900
b2	1. 180	1. 310	1.440
С	0.480	0.500	0.560
c1	1.290	1. 300	1. 320
D	9.800	10.000	10.200
E	6.400	6. 500	6. 600
E1	9.000	9. 100	9. 200
е	2. 420	2.540	2. 660
e1	4.840	5. 080	5. 320
Н	2.730	2. 800	2. 870
H1	2.400	2.500	2. 600
L	13.020	13. 370	13.720
R	3.500	3. 600	3. 730
R1	1.400	1.500	1.600
U	1.650	1.750	1.850
V	0.580	0.680	0. 780
θ 1	2°	2.5°	3°
θ2	6.5°	7°	7.5°

Symbo1	Dimensions (mm)
A	10.0±0.3
A1	8.0±0.2
A2	0.94±0.1
A3	8.7±0.1
В	15.6±0.4
B1	13.2±0.2
С	4.5±0.2
C1	1.3±0.2
D	0.8±0.2
D1	0.5±0.1
Е	10.0±0.3
F	2.8±0.1
Н	3.6±0.1
К	3.1±0.2
L	1.3±0.4
M	1.38±0.1
M1	1.28±0.1
N	2.54 (typ)
P	2.4±0.3
Q	9.15±0.25

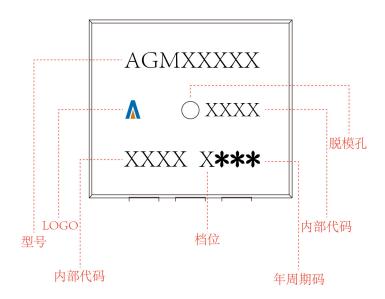


# TO-220 Marking Instructions:

# Model1:



## Model2:





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